

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/07/2022

Details for "TAS3251DKQ"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TAS3251DKQ	NIPDAU	Level-3-260C-168 HR	TI MALAYSIA A/T	DKQ   56	7.5x18.41x2.59	722.6

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	2.024672	99.99758	999976	0.280185	2802
Copper and Its Alloys	Iron	7439-89-6	0.000009	0.000445	4	0.000001	0
Nickel and Its Alloys	Nickel	7440-02-0	0.000004	0.000198	2	0.000001	0
Other Inorganic Materials	Sulfur	7704-34-9	0.000003	0.000148	1	0	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.000005	0.000247	2	0.000001	0
Precious Metals	Silver	7440-22-4	0.000028	0.001383	14	0.000004	0
Sub-Total			2.024721	100	1000000	0.280192	2802
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	4.388155	85.000005	850000	0.607258	6073
Thermoplastics	Epoxy	85954-11-6	0.77438	14.999995	150000	0.107163	1072
Sub-Total			5.162535	100	1000000	0.714421	7144
<b>Die Attach Adhesive 2</b>							
Precious Metals	Silver	7440-22-4	1.360493	85	850000	0.188273	1883
Thermoplastics	Epoxy	85954-11-6	0.240087	15	150000	0.033225	332
Sub-Total			1.60058	100	1000000	0.221497	2215
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	38.546075	97.585	975850	5.334222	53342
Copper and Its Alloys	Iron	7439-89-6	0.9085	2.3	23000	0.125723	1257
Copper and Its Alloys	Phosphorus	7723-14-0	0.005925	0.015	150	0.00082	8
Zinc and Its Alloys	Zinc	7440-66-6	0.0395	0.1	1000	0.005466	55
Sub-Total			39.5	100	1000000	5.466232	54662
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.299628	95.12	951200	0.041464	415
Precious Metals	Gold	7440-57-5	0.002457	0.78	7800	0.00034	3
Precious Metals	Palladium	7440-05-3	0.012915	4.1	41000	0.001787	18
Sub-Total			0.315	100	1000000	0.043591	436
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	569.662241	88	880000	78.833057	788331
Other Plastics and Rubber	Carbon Black	1333-86-4	2.589374	0.4	4000	0.358332	3583
Thermoplastics	Epoxy	85954-11-6	75.091841	11.6	116000	10.39163	103916
Sub-Total			647.343456	100	1000000	89.583019	895830
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	20.359868	100	1000000	2.817513	28175
Sub-Total			20.359868	100	1000000	2.817513	28175
<b>Semiconductor Device 2</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	6.312324	100	1000000	0.873535	8735
Sub-Total			6.312324	100	1000000	0.873535	8735
<b>Total</b>			722.618484			100	1000000

**Important Note**

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. [See Glossary of Terms for more details.](#)

**Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.